

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 05/30/2022

Details for "DS92LV2412SQX/NOPB"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
DS92LV2412SQX/NOPB	SN	Level-3-260C-168 HR	Texas Instruments Electronics	NKB 60	9 x 9 x 0.8	233.2

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.650405	97.535098	975351	0.278905	2789
Nickel and Its Alloys	Nickel	7440-02-0	0.000003	0.00045	4	0.000001	0
Not Categorized	Proprietary Materials		0.000073	0.010947	109	0.000031	0
Precious Metals	Gold	7440-57-5	0.000343	0.051436	514	0.000147	1
Precious Metals	Palladium	7440-05-3	0.015999	2.399219	23992	0.006861	69
Precious Metals	Silver	7440-22-4	0.000019	0.002849	28	0.000008	0
Sub-Total			0.666842	100	1000000	0.285953	2860
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	1.29125	74.999985	750000	0.55371	5537
Thermoplastics	Epoxy	85954-11-6	0.430417	25.000015	250000	0.18457	1846
Sub-Total			1.721667	100	1000000	0.73828	7383
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	135.828	97.02	970200	58.245319	582453
Copper and Its Alloys	Iron	7439-89-6	3.64	2.6	26000	1.560893	15609
Copper and Its Alloys	Phosphorus	7723-14-0	0.21	0.15	1500	0.090052	901
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.042	0.03	300	0.01801	180
Zinc and Its Alloys	Zinc	7440-66-6	0.28	0.2	2000	0.120069	1201
Sub-Total			140	100	1000000	60.034342	600343
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.766	100	1000000	0.328474	3285
Sub-Total			0.766	100	1000000	0.328474	3285
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	77.573714	90.5	905000	33.264906	332649
Thermoplastics	Epoxy	85954-11-6	8.143097	9.5	95000	3.491896	34919
Sub-Total			85.716811	100	1000000	36.756803	367568
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	4.328537	100	1000000	1.856149	18561
Sub-Total			4.328537	100	1000000	1.856149	18561
Total			233.199857			100	1000000

Important Note
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.